Here	SPIRE	Ref: SPIRE-RAL-NOT-000983 Issue: 2.0
Will Go	Definition of the SPIRE CQM Delivered for system level testing B. Swinyard	Date: 19 Feb 2002 Page: 1 of 2

The following tables define the form and capability of the SPIRE instrument to be delivered for EQM testing. Updated 19/2/2002 to reflect expected form of QM1 HSFCU Unit: HSFPU

Subsystem	Delivered CQM Form/Capability
/component	
Structure/baffles/wiring standoffs etc	Flight Representative
Mirrors	Flight Representative
Filters	Flight representative
Beam steering mirror	Form and fit compliant
C C	Functionally representative in at least one axis
	No redundancy
	Electrical interfaces compliant
	Thermal conduction flight representative
	Thermal dissipation may not be flight representative
3He Fridge/thermal straps	Form and fit compliant
5	Functionally fully flight representative
	All parts flight build standard except thermometers and
	heaters will be commercial/industrial grade
300 mK Thermal control system	None
Photometer LW array	Flight representative
Photometer MW array	Form and fit compliant
	Resistors used to represent detectors.
	Temperature monitors functionally representative (TBC)
Photometer SW array	Ditto
SMEC	Form and fit compliant
SMEO	Functionally representative – mirror travel TBD
	Electrical interfaces must be compliant
	Thermal dissipation may not be flight representative
Spectrometer SW array	As P/MW and P/SW arrays
Photometer I W array	Flight representative
Photometer Calibrator	Form and fit compliant
	Electrical interfaces compliant
	Thermal interfaces compliant
	No redundancy (TBC)
Spectrometer Calibrator	Form and fit compliant
	Functionally representative
	Flectrical interfaces compliant
	Thermal interfaces compliant
	No redundancy (TBC)
Shutter	Form and fit compliant
Shutter	
	Electrical interfaces compliant
IFFT Enclosures	Elight Representative
IFET Modules and IFET box RE filter	Form and fit compliant
modulos	Functionally representative
modules	Flectrical interfaces compliant
	Thermal interfaces compliant
	Only IEETs for "live" detector channels will be provided
	Resistors for thermal dissination in other channels will be
	provided (TRC)
EPI I RE Eilters	
Thermometry	Flight representative
EDI Linternal harnesses	Flight representative
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Unit: HSDCU

Subsystem /component	Delivered CQM Form/Capability
External structure/mechanical interfaces	Flight representative
Electrical Interfaces	Prime interfaces flight representative No redundant interfaces implemented
Functionality	Near flight performance on prime side No redundant side implemented
Electrical Component Level	Commercial/industrial level parts with near flight performance

Unit: HSFCU

Subsystem	Delivered CQM Form/Capability
rcomponent	
External structure/mechanical interfaces	Not form and fit compliant - some of the sub-units will not be
	housed within the FCU flight envelope
Electrical Interfaces	Interfaces to S/C not flight representative – EGSE replaces
	power supply unit
	Prime instrument interfaces flight representative
	No redundant interfaces implemented
Functionality	Near flight performance on prime side
	No redundant side implemented
Electrical Component Level	Commercial/industrial level parts with near flight performance

Unit: HSDPU (this unit will also be used for the AVM)

Subsystem /component	Delivered CQM Form/Capability
External structure/mechanical interfaces	Flight Representative
Electrical Interfaces	Prime interfaces flight representative
Functionality	No redundant interfaces implemented
Functionality	No redundant side implemented
Electrical Component Level	Commercial/industrial level parts with near flight performance

Unit: HSWIH (Warm interconnect harness)

Subsystem	Delivered CQM Form/Capability
/component	
External structure/mechanical interfaces	Flight representative
Electrical Interfaces	Flight representative
Functionality	Near flight performance
Electrical Component Level	Commercial/industrial level parts with near flight performance